

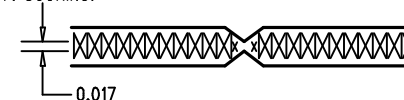
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.035	26	+	PLTD
0.094	3	×	PLTD
0.07	2	□	NPLTD
0.015	71	◇	PLTD
0.125	6	⊗	PLTD
0.04	9	⊗	PLTD
0.05	20	A	PLTD
0.08	4	B	PLTD
0.064	1	C	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY	1630 McCarthy Blvd Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE			
DRAWN					
CHECK					
DESIGN	KIM T.	02-29-02			
ENGR	STEVE M.	02-29-02			
			TITLE: FABRICATION DRAWING DUAL SMART CARD INTERFACE		
SCALE = NONE			SIZE A DEMO DC465A-1*LTC1955EUH REV. A		
DES- 0000			SHT 1 of 1		